



SOT533

plastic single-ended package (IPAK); 3 leads (in-line)

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	IPAK
Package type industry code	IPAK
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-251
Mounting method type	T (through-hole mount)
Issue date	14-2-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.98	-	6	6.22	mm
E	package width	6.47	-	6.6	6.73	mm
A ₂	package height	2.22	-	2.3	2.38	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

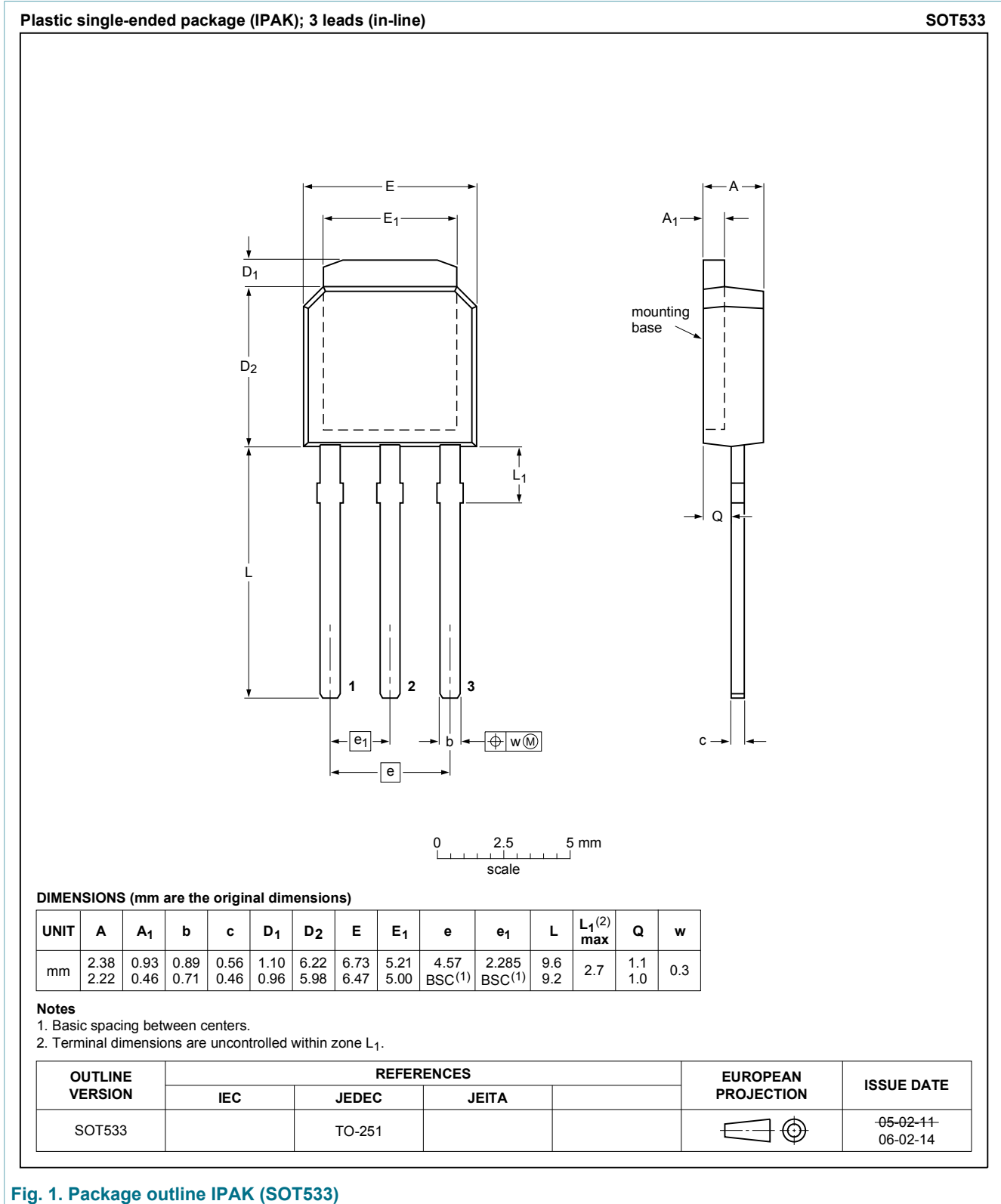


Fig. 1. Package outline IPAK (SOT533)

3. Legal information

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